SV10

Rectifier Diode

Replaces January 2000 version, issue DS4084-3.0

DS4084-4.0 June 2004

APPLICATIONS

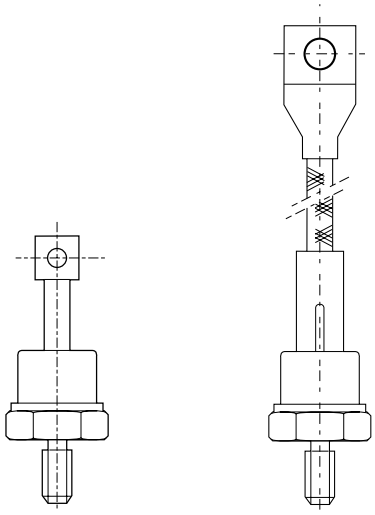
- Rectification
- Freewheel Diode
- DC Motor Control
- Power Supplies
- Welding
- Battery Chargers

KEY PARAMETERS

V_{RRM}	2500V
$I_{F(AV)}$	180A
I_{FSM}	2200A

FEATURES

- High Surge Capability



Outline type codes: DO8C and DO8.
See Package Details for further information.

Fig. 1 Package outline

VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage V_{RRM} V	Conditions
SV10 25 M or K(R) SV10 20 M or K(R) SV10 16 M or K(R)	2500 2000 1600	$V_{RSM} = V_{RRM} + 100V$

Lower voltage grades available.
M for M12 thread. K for 1/2" - 20UNF thread, R for reverse polarity.
Add C to type number for DO8C package.

CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
Single Side Cooled				
$I_{F(AV)}$	Mean forward current	Half wave resistive load, T_{case} = 100°C	180	A
$I_{F(RMS)}$	RMS value	T_{case} = 100°C	283	A
I_F	Continuous (direct) forward current	T_{case} = 100°C	233	A

SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; T_{case} = 175°C	1.76	kA
I^2t	I^2t for fusing	V_R = 50% V_{RRM} - 1/4 sine	14.9 x 10^3	A^2s
I_{FSM}	Surge (non-repetitive) forward current	10ms half sine; T_{case} =175°C	2.2	kA
I^2t	I^2t for fusing	V_R = 0	24.0 x 10^3	A^2s

THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.23	°C/W
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 15.0Nm with mounting compound	-	0.08	°C/W
T_{vj}	Virtual junction temperature	On-state (conducting)	-	175	°C
		Reverse (blocking)	-	175	°C
T_{stg}	Storage temperature range		-55	200	°C
-	Mounting Torque		12.0	15.0	Nm

CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
V_{FM}	Forward voltage	At 300A peak, T_{case} = 25°C	-	1.5	V
I_{RRM}	Peak reverse current	At V_{RRM}, T_{case} = 175°C	-	20	mA
Q_S	Total stored charge	I_F = 100A, dI_{RR}/dt = 20A/µs, T_{case} = 25°C	300*	-	µC
I_{RM}	Peak recovery current		100*	-	A
t_{rr}	reverse recovery time		6.5*	-	µs
V_{TO}	Threshold voltage	At T_{vj} = 175°C	-	1.1	V
r_T	Slope resistance	At T_{vj} = 175°C	-	1.3	mΩ

**Typical values.*

CURVES

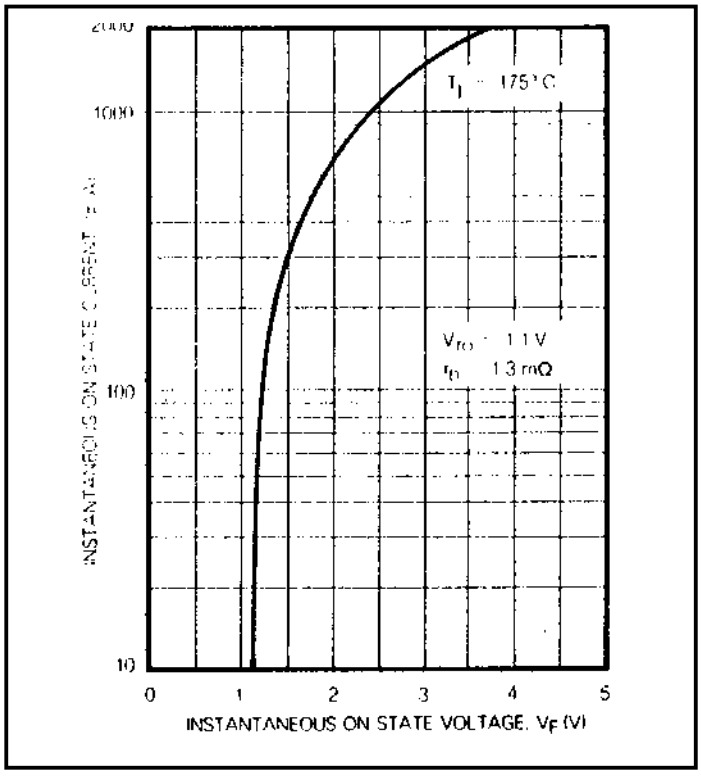


Fig. 2 Maximum (limit) forward conduction characteristic

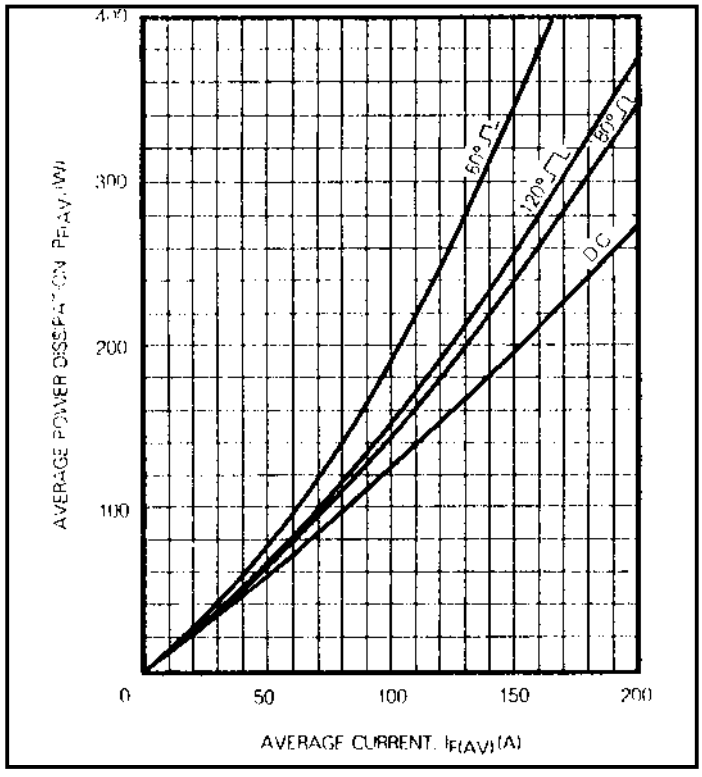


Fig. 3 Maximum forward power dissipation

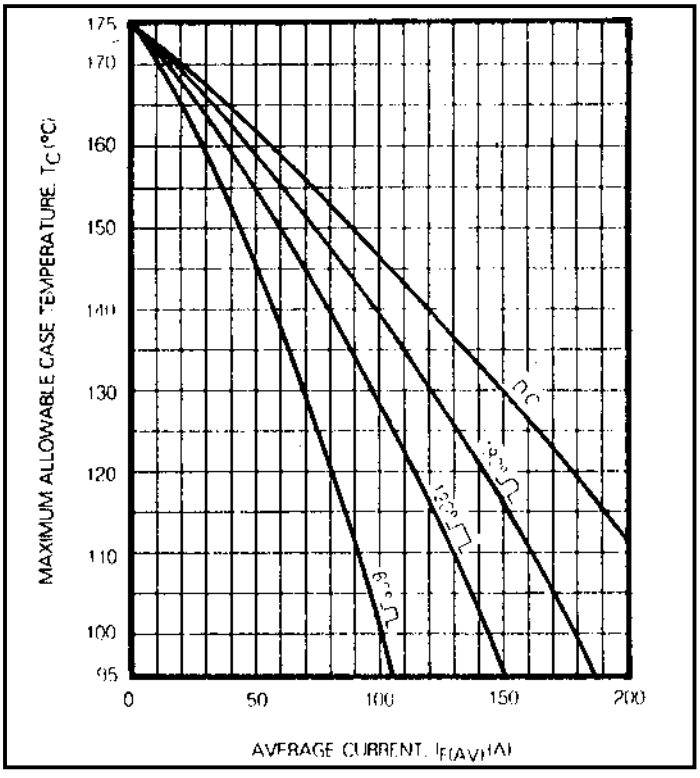


Fig. 4 Maximum (limit) forward case temperature

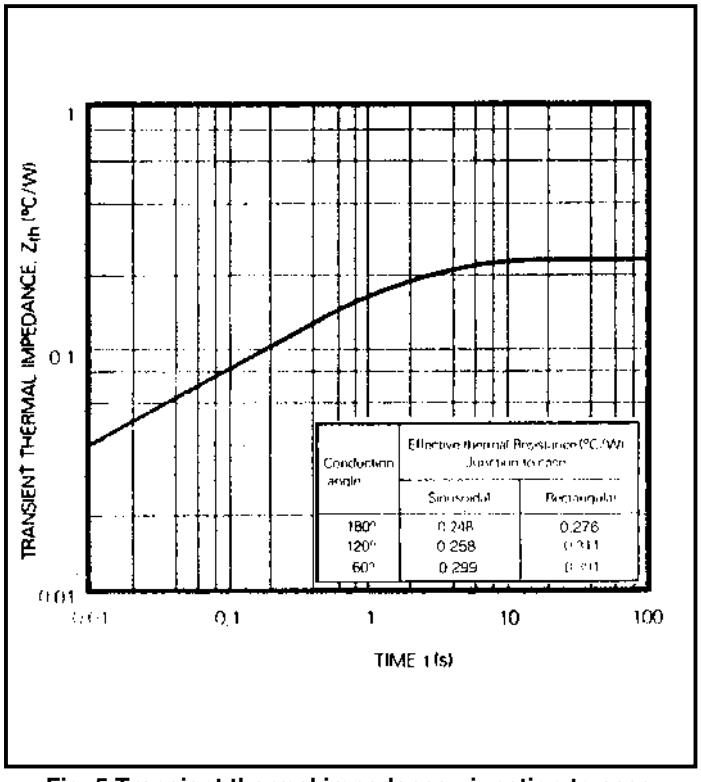


Fig. 5 Transient thermal impedance - junction to case

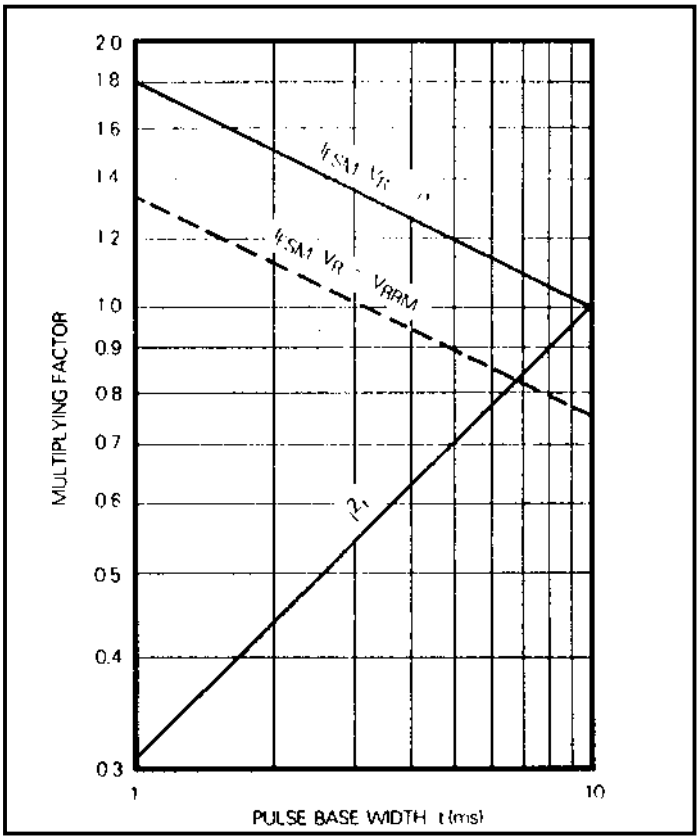


Fig. 6 Multiplying factor for non-repetitive sub-cycle forward current and I^2t rating

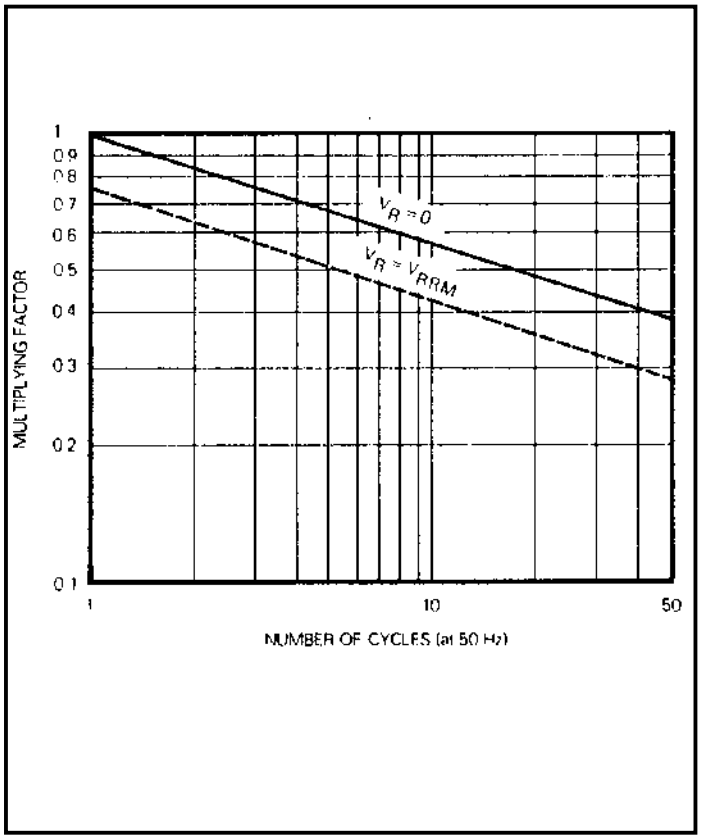
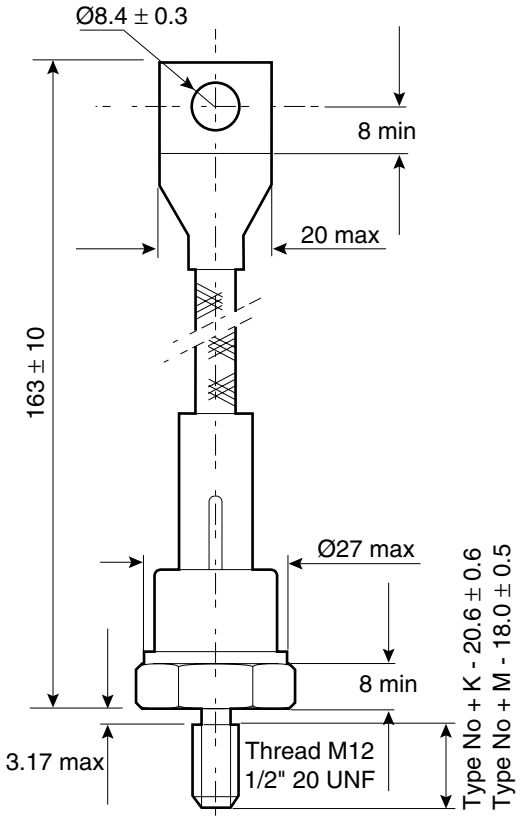


Fig. 7 Multiplying factor for non-repetitive forward current

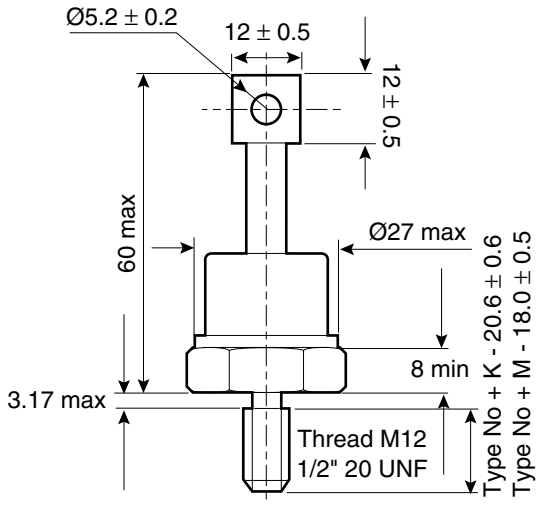
PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



Nominal weight: 120g
Mounting torque: 15Nm ±10%

Package outine type code: DO8



Nominal weight: 120g
Mounting torque: 15Nm ±10%

Package outine type code: DO8C

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.

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